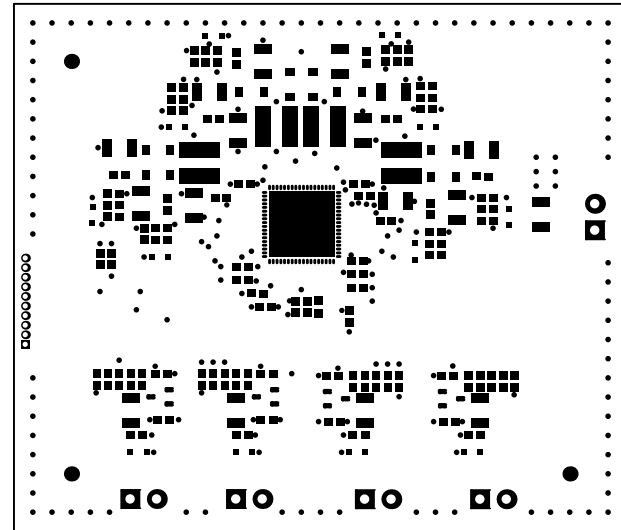
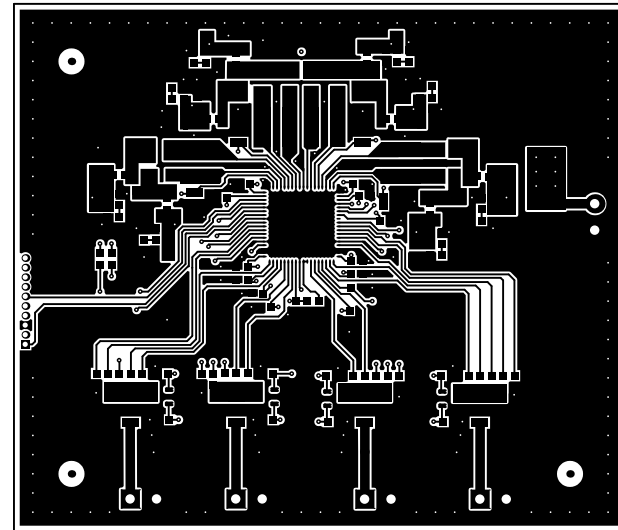


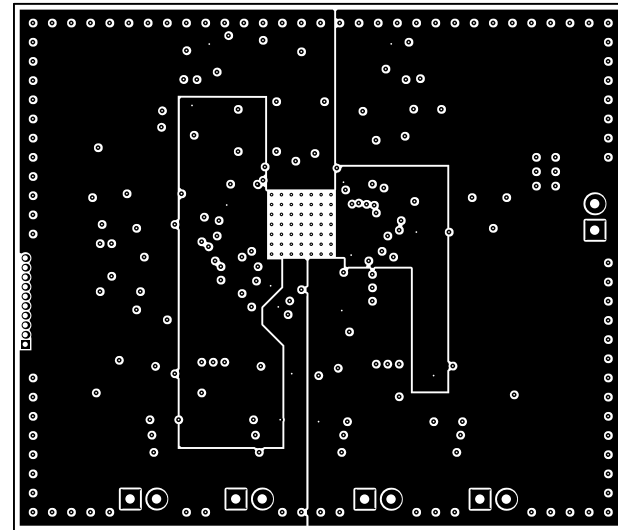
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Top Overlay	GENERATED : 3/3/2017	3:42:18 PM	TEXAS INSTRUMENTS



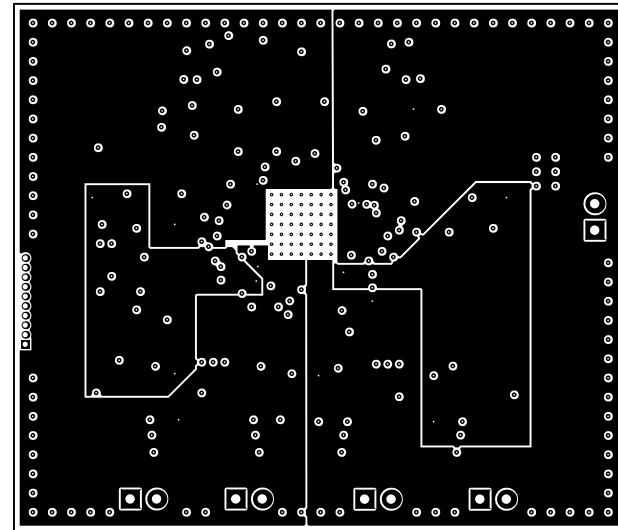
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Top Solder Mask	GENERATED : 3/3/2017 3:42:18 PM	TEXAS INSTRUMENTS	



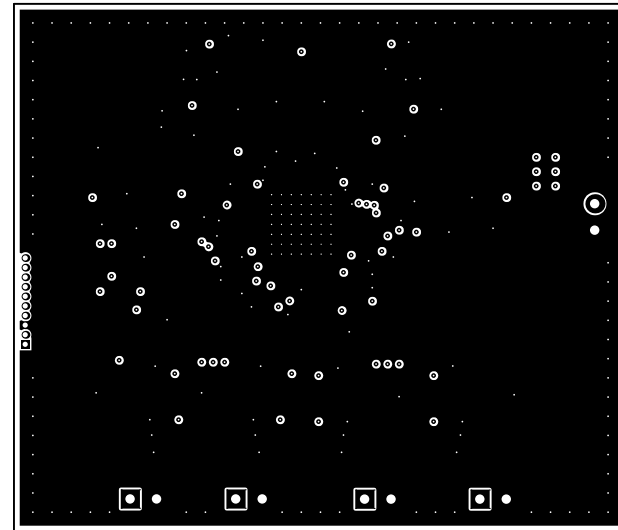
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Top Layer	GENERATED : 3/3/2017 3:42:18 PM	TEXAS INSTRUMENTS	



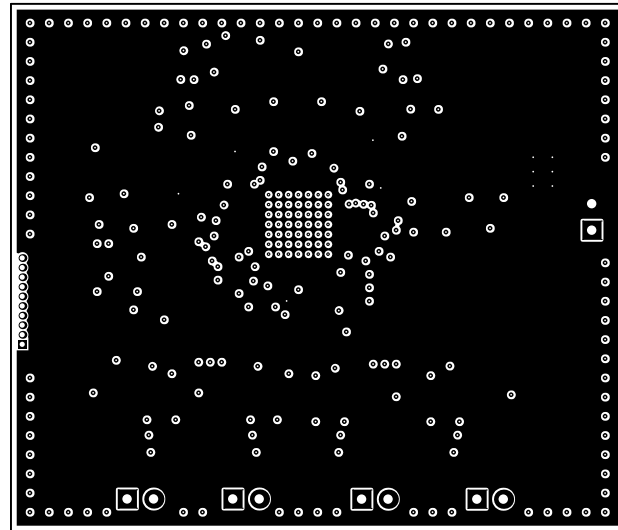
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Signal Layer 1	GENERATED : 3/3/2017 3:42:19 PM	TEXAS INSTRUMENTS	



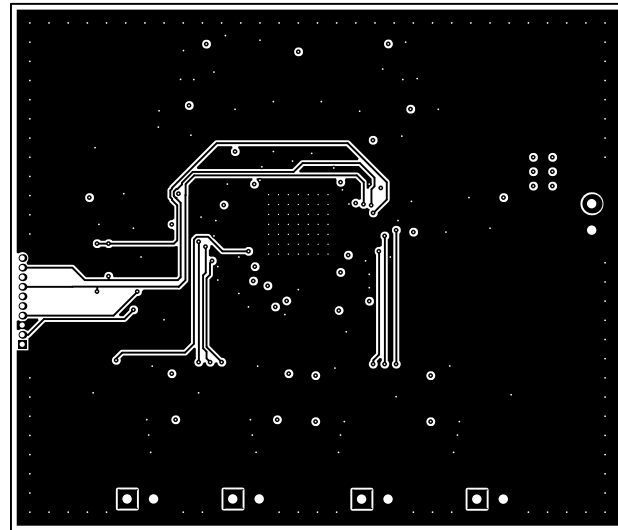
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Signal Layer 2	GENERATED : 3/3/2017 3:42:19 PM	TEXAS INSTRUMENTS	



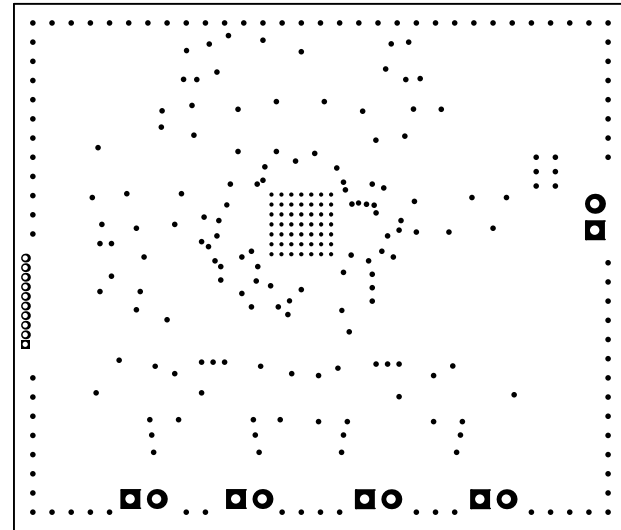
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Signal Layer 3	GENERATED : 3/3/2017 3:42:19 PM	TEXAS INSTRUMENTS	



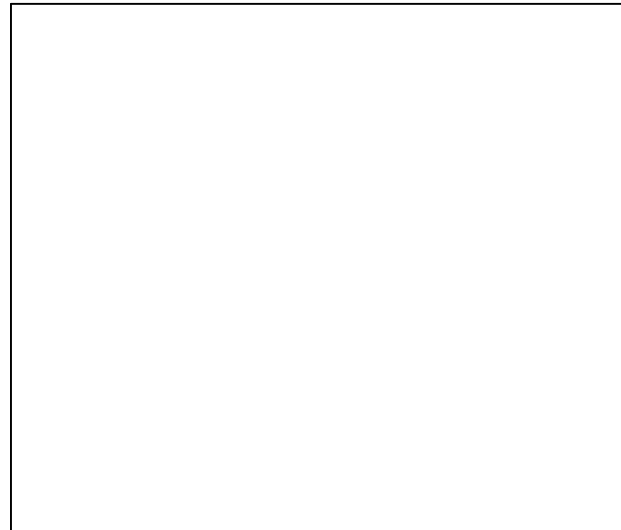
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Signal Layer 4	GENERATED : 3/3/2017 3:42:19 PM	TEXAS INSTRUMENTS	



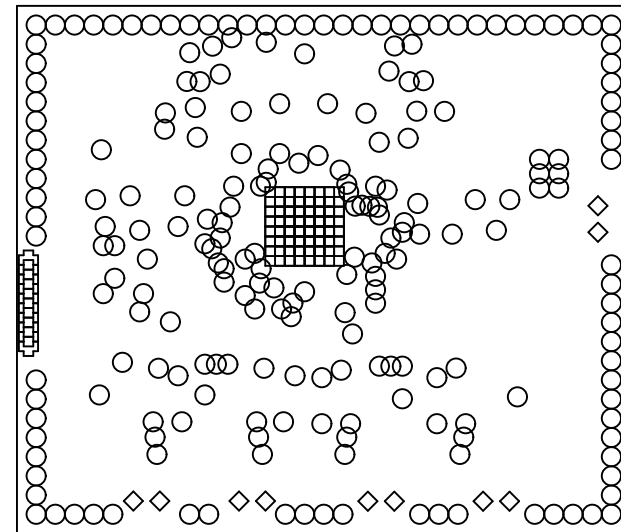
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Bottom Layer	GENERATED : 3/3/2017 3:42:19 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/3/2017	3:42:20 PM	TEXAS INSTRUMENTS

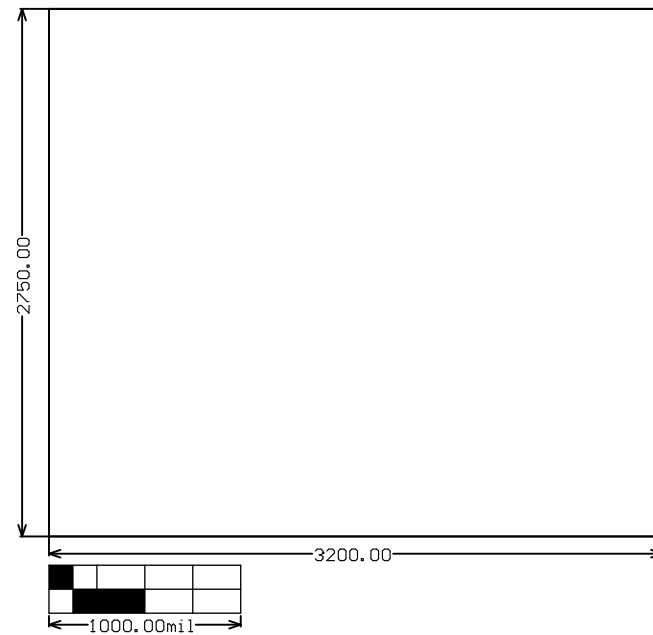


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Bottom Overlay	GENERATED : 3/3/2017	3:42:20 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	49	7.87mil (0.200mm)	PTH	Round
○	226	10.00mil (0.254mm)	PTH	Round
⊗	10	28.74mil (0.730mm)	PTH	Round
◇	10	50.00mil (1.270mm)	PTH	Round
	295 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Drill Drawing	GENERATED : 3/3/2017	3:42:20 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD216	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD216		
PLOT NAME = Board Dimensions	GENERATED : 3/3/2017	3:42:20 PM	TEXAS INSTRUMENTS

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